

### Features

- Low gate charge
- Simple drive requirement

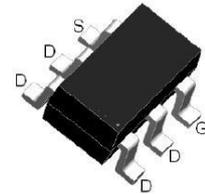
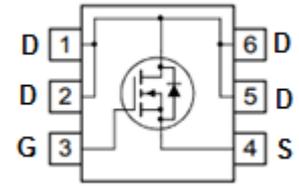
HF

### Applications

- Power switching application
- Hard switching and high frequency circuits
- Uninterruptible power supply

### Mechanical Data

- Case: SOT-23-6L
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



SOT-23-6L

### Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL12K0N20-6L	SOT-23-6L	3000 pcs / Tape & Reel	12K0N20

### Maximum Ratings (@ T<sub>A</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	200	V
Gate-to-Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	0.9	A
Pulsed Drain Current <sup>*1</sup>	I <sub>DM</sub>	3.6	A

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>D</sub>	1.25	W
Thermal Resistance Junction-to-Air*3	R <sub>θJA</sub>	100	°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-55 ~ +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 ~ +150	°C

### Electrical Characteristics (@ T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
V <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	200	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 160V, V <sub>GS</sub> = 0V	-	-	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
<b>On Characteristics</b> <sup>*2</sup>						
R <sub>DS(ON)</sub>	Static Drain-Source On-resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.5A	-	-	1.2	Ω
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2	-	4	V
<b>Dynamic Characteristics</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>GS</sub> = 0V	-	135	-	pF
C <sub>OSS</sub>	Output Capacitance	V <sub>DS</sub> = 100V	-	13	-	
C <sub>RSS</sub>	Reverse Transfer Capacitance	f = 1.0MHz	-	5	-	
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> = 100V, V <sub>GS</sub> = 10V R <sub>G</sub> = 1Ω, I <sub>D</sub> = 1A	-	4.4	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	6.6	-	
t <sub>d(OFF)</sub>	Turn-Off Delay Time		-	10	-	
t <sub>f</sub>	Turn-Off Fall Time		-	9.2	-	
Q <sub>G</sub>	Total Gate-Charge	V <sub>DD</sub> = 100V	-	4.2	-	nC
Q <sub>GS</sub>	Gate to Source Charge	V <sub>GS</sub> = 10V	-	1.1	-	
Q <sub>GD</sub>	Gate to Drain (Miller) Charge	I <sub>D</sub> = 0.5A	-	0.7	-	
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>*2</sup>	I <sub>SD</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%
3. Surface Mounted on 1" x 1" FR4 Board

Ratings and Characteristics Curves (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

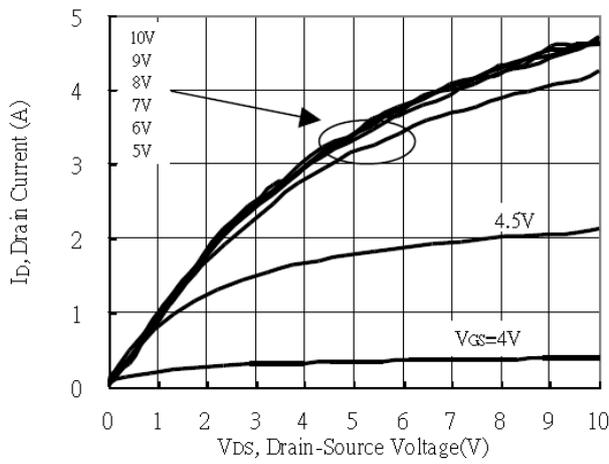


Fig 1 Typical Output Characteristics

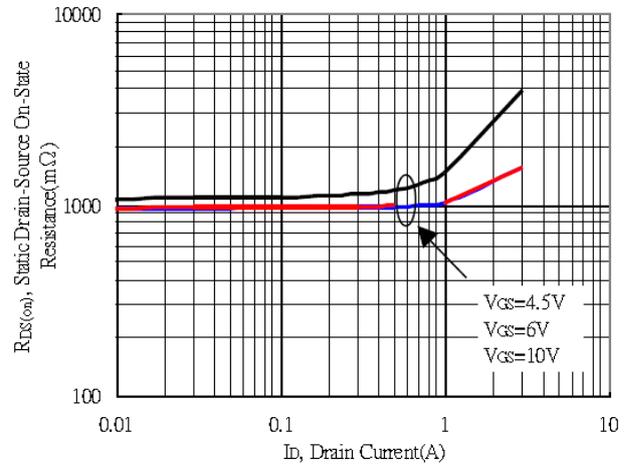


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

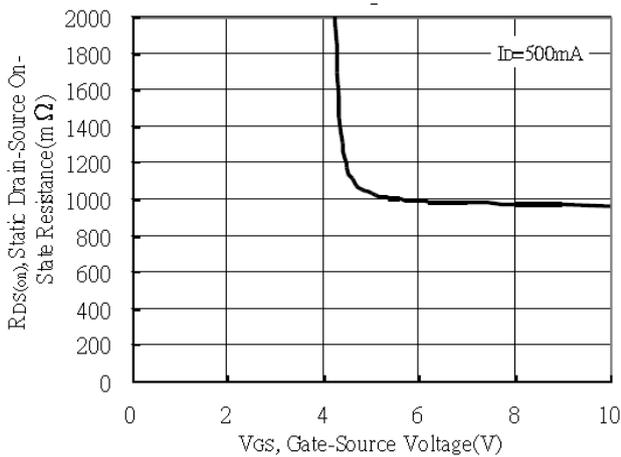


Fig 3 On-Resistance vs. Gate-Source Voltage

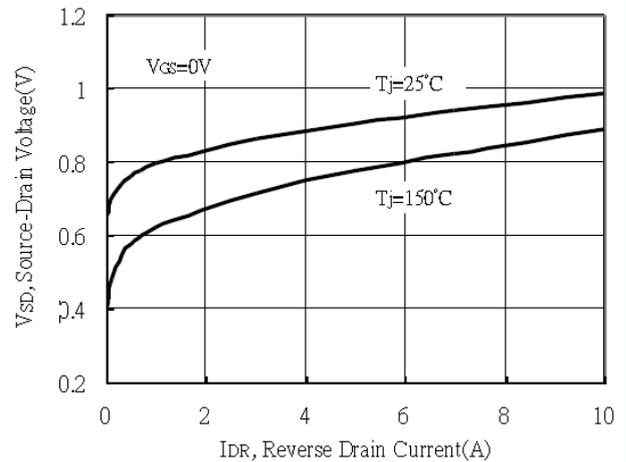


Fig 4 Body-Diode Characteristics

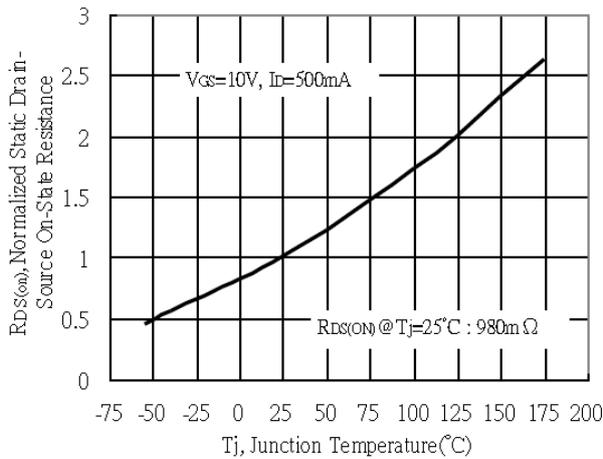


Fig 5 On-Resistance vs. Junction Temperature

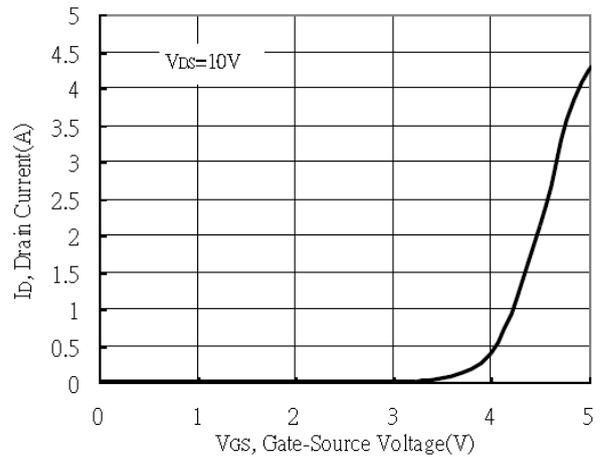


Fig 6 Transfer Characteristics

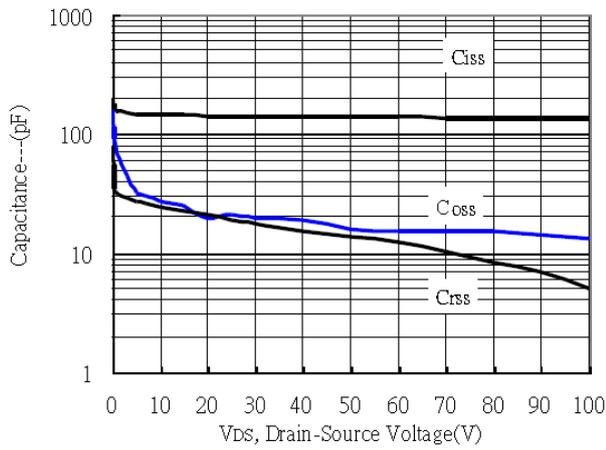


Fig 7 Capacitance Characteristics

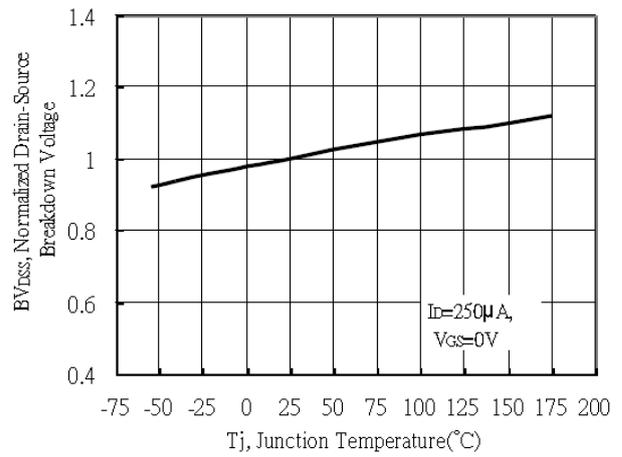


Fig 8 Drain-Source vs. Junction Temperature

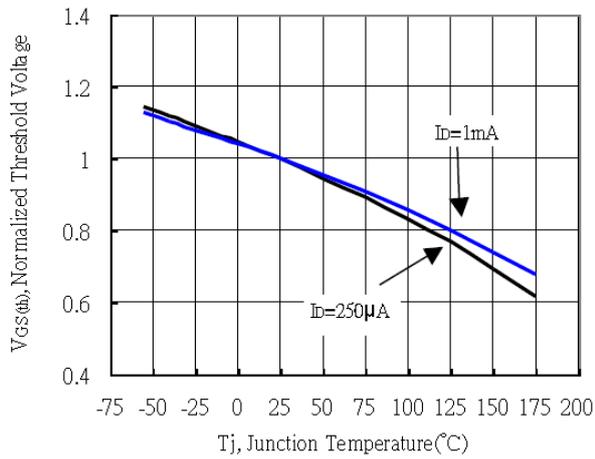


Figure 9 Gate Voltage vs. Junction Temperature

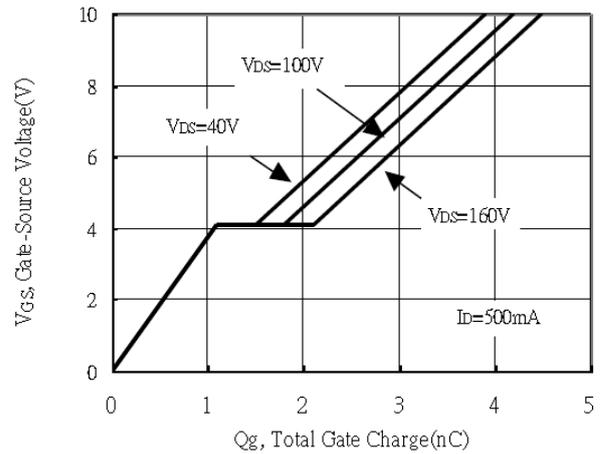
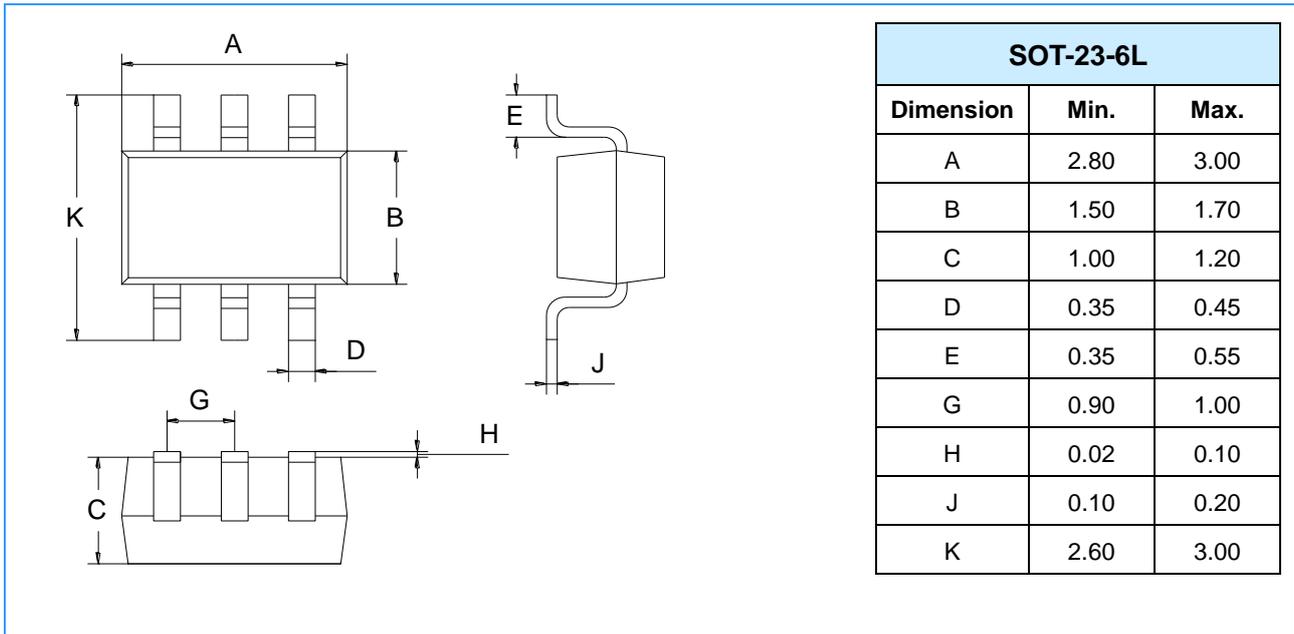
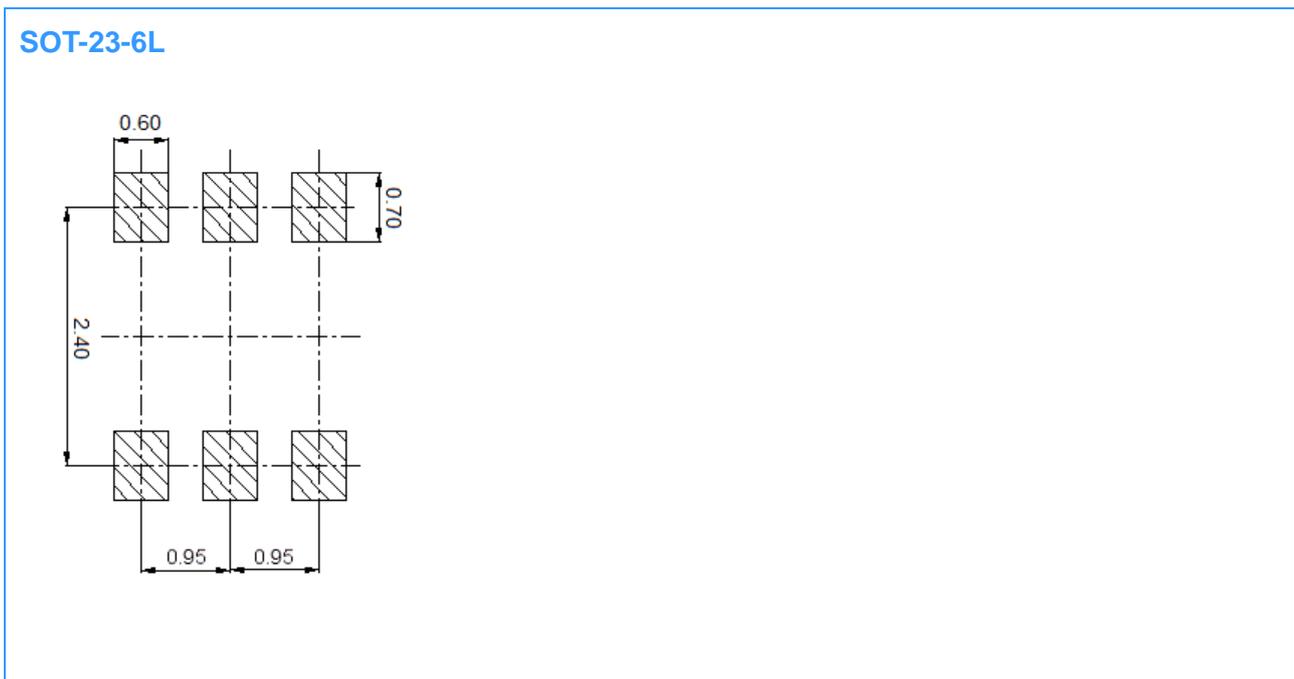


Figure 10 Gate-Charge Characteristics

**Package Outline Dimensions** (Unit: mm)



**Mounting Pad Layout** (Unit: mm)



**Important Notice**

Changzhou Galaxy Century Microelectronics (GME) reserves the right to make changes without further notice to any product information (copyrighted) herein to make corrections, modifications, improvements, or other changes. GME does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others.